COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: [No Variations]

<table>
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<th>PCB VIEWED FROM BOTTOM SIDE</th>
<th>BOARD #: TIDA-01492</th>
<th>REV: E1</th>
<th>SUN REV: Not In VersionControl</th>
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<td>TID #: TIDA-01492</td>
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PLOT NAME = Bottom Assembly Drawing  GENERATED : 11/27/2017  4:03:33 PM  TEXAS INSTRUMENTS
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